SN54ALS157A, SN54ALS158 SN74ALS157A, SN74ALS158, SN74AS157, SN74AS158 QUADRUPLE 1-OF-2 DATA SELECTORS/MULTIPLEXERS

SDAS081C - APRIL 1982 - REVISED DECEMBER 1994

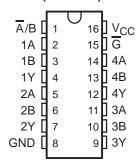
- Buffered Inputs and Outputs
- Package Options Include Plastic Small-Outline (D) Packages, Ceramic Chip Carriers (FK), and Standard Plastic (N) and Ceramic (J) 300-mil DIPs

description

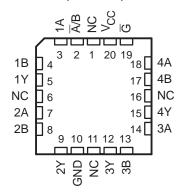
These data selectors/multiplexers contain inverters and drivers to supply full data selection to the four output gates. A separate strobe (\overline{G}) input is provided. A 4-bit word is selected from one of two sources and is routed to the four outputs. The 'ALS157A and SN74AS157 present true data. The 'ALS158 and SN74AS158 present inverted data to minimize propagation delay time.

The SN54ALS157A and SN54ALS158 are characterized for operation over the full military temperature range of -55°C to 125°C. The SN74ALS157A, SN74ALS158, SN74AS157, and SN74AS158 are characterized for operation from 0°C to 70°C.

SN54ALS157A, SN54ALS158 . . . J PACKAGE SN74ALS157A, SN74ALS158, SN74AS157, SN74AS158 . . . D OR N PACKAGE (TOP VIEW)



SN54ALS157A, SN54ALS158 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

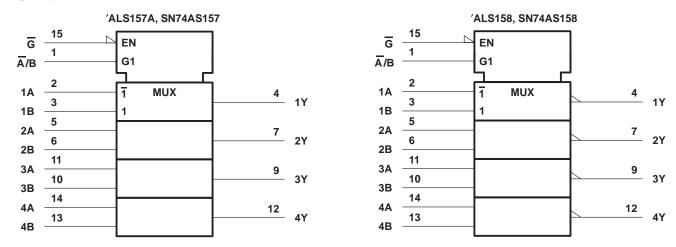
FUNCTION TABLE

	INP	JTS		OUTPUT Y			
G	A/B	DA	TΑ	'ALS157A	'ALS158		
G	A/B	Α	В	SN74AS157	SN74AS158		
Н	Χ	Х	Χ	L	Н		
L	L	L	Χ	L	Н		
L	L	Н	Χ	Н	L		
L	Н	Х	L	L	Н		
L	Н	Х	Н	Н	L		

SN54ALS157A, SN54ALS158 SN74ALS157A, SN74ALS158, SN74AS157, SN74AS158 QUAD 1-OF-2 DATA SELECTORS/MULTIPLEXERS

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logic symbols†

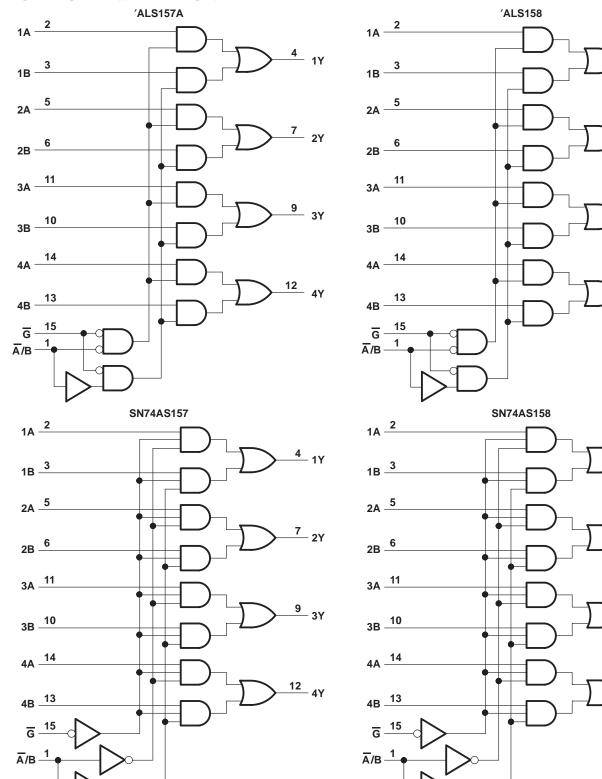


 $[\]dagger$ These symbols are in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the D, J, and N packages.

7 2Y

9 3Y

logic diagrams (positive logic)



Pin numbers shown are for the D, J, and N packages.



12 4Y

SN54ALS157A, SN54ALS158 SN74ALS157A, SN74ALS158, SN74AS157, SN74AS158 QUAD 1-OF-2 DATA SELECTORS/MULTIPLEXERS

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V _{CC}		 7 V
Input voltage, V _I		 7 V
Operating free-air temperature range, T _A :		
	SN74ALS157A, SN74ALS158	
Storage temperature range		_65°C to 150°C

recommended operating conditions

			54ALS15 54ALS1		SN74ALS157A SN74ALS158			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
VCC	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage	2			2			V
V _{IL}	Low-level input voltage			0.7			0.8	V
IOH	High-level output current			-0.4			-0.4	mA
loL	Low-level output current			4			8	mA
TA	Operating free-air temperature	-55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PA	RAMETER	TEST CONDITIONS			SN54ALS157A SN54ALS158			SN74ALS157A SN74ALS158			
				MIN	TYP‡	MAX	MIN	TYP [‡]	MAX		
VIK		V _{CC} = 4.5 V,	$I_{I} = -18 \text{ mA}$			-1.2			-1.2	V	
Vон		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V},$	$I_{OH} = -0.4 \text{ mA}$	VCC -	2		VCC -2)		V	
V	I _{OL} = 4		I _{OL} = 4 mA		0.25	0.4		0.25	0.4	V	
VOL		V _{CC} = 4.5 V	I _{OL} = 8 mA					0.35	0.5).5	
Ц		$V_{CC} = 5.5 \text{ V},$	V _I = 7 V			0.1			0.1	mA	
lіН		$V_{CC} = 5.5 \text{ V},$	V _I = 2.7 V			20			20	μΑ	
II∟		V _{CC} = 5.5 V,	V _I = 0.4 V			-0.1			-0.1	mA	
IO§		V _{CC} = 5.5 V,	V _O = 2.25 V	-20		-112	-30		-112	mA	
la a	'ALS157A	Vac EEV	See Note 1		6	11		6	11	A	
ICC	'ALS158	V _{CC} = 5.5 V,	See Note 1		5	10		5	10	mA	

[‡] All typical values are at V_{CC} = 5 V, T_A = 25°C.

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

[§] The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, I_{OS}. NOTE 1: I_{CC} is measured with 4.5 V applied to all inputs and all outputs open.

switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 5 \text{ V},$ $C_L = 50 \text{ pF},$ $R_L = 500 \Omega,$ $T_A = 25^{\circ}\text{C}$	C _L R _L	= 50 pF = 500 £		UNIT	
	, ,	('ALS157A	SN54AL	S157A	SN74AL	S157A	
			TYP	MIN	MAX	MIN	MAX	
^t PLH	A D	V	9	4	17	4	14	
t _{PHL}	A or B	Y	6	2	15	2	12	ns
^t PLH	Ā/B	V	15	7	28	7	24	
^t PHL	A/B	Y	9	4	20	4	17	ns
^t PLH	G	V	14	7	25	7	20	ns
t _{PHL}	9	r	10	4	18	4	13	115

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 5 \text{ V},$ $C_L = 50 \text{ pF},$ $R_L = 500 \Omega,$ $T_A = 25^{\circ}\text{C}$	C _L R _L	V_{CC} = 4.5 V to 5.5 V, C_L = 50 pF, R_L = 500 Ω , T_A = MIN to MAX [†]			
	, ,	(=== ,	'ALS158	SN54AL	.S158	SN74AL	S158	
			TYP	MIN	MAX	MIN	MAX	
^t PLH	A D	V	9	4	18	4	15	
^t PHL	A or B	Y	5	2	12	2	8	ns
^t PLH	Ā/B	V	13	5	22	5	18	
t _{PHL}	A/B	Y	13	5	22	5	18	ns
^t PLH	G	V	13	5	22	5	18	20
^t PHL	9	I	13	5	22	5	18	ns

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

SN54ALS157A, SN54ALS158 SN74ALS157A, SN74ALS158, SN74AS157, SN74AS158 QUAD 1-OF-2 DATA SELECTORS/MULTIPLEXERS

SDAS081C - APRIL 1982 - REVISED DECEMBER 1994

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V _{CC}	7 V
Input voltage, V ₁	7 V
Operating free-air temperature range, T _A : SN74AS157, SN74AS158	
Storage temperature range	

recommended operating conditions

			174AS15 174AS15		UNIT
		MIN	NOM	MAX	
VCC	Supply voltage	4.5	5	5.5	V
VIH	High-level input voltage	2			V
V_{IL}	Low-level input voltage			0.8	V
I _{OH}	High-level output current			-2	mA
lOL	Low-level output current			20	mA
TA	Operating free-air temperature	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	PARAMETER	TEST COND	TEST CONDITIONS			UNIT	
				MIN TYP‡	MAX		
VIK		V _{CC} = 4.5 V,	I _I = –18 mA		-1.2	V	
Vон		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V},$	$I_{OH} = -2 \text{ mA}$	V _{CC} -2		V	
VOL		V _{CC} = 4.5 V,	$I_{OL} = 20 \text{ mA}$	0.35	0.5	V	
	Ā/B	V 55V			0.2		
l _l	A, B, or G	$V_{CC} = 5.5 \text{ V},$	V _I = 7 V		0.1	mA	
	Ā/B	.,,	.,,		40		
lн	A, B, or G	$V_{CC} = 5.5 V,$	$V_{I} = 2.7 V$		20	μΑ	
	Ā/B	.,			-1		
ΊL	A, B, or \overline{G}	$V_{CC} = 5.5 V,$	$V_{I} = 0.4 V$		-0.5	mA	
IO§	•	V _{CC} = 5.5 V,	V _O = 2.25 V	-30	-112	mA	
	SN74AS157	V 55V		17.5	28	A	
ICC	SN74AS158	V _{CC} = 5.5 V		15.6	22.5	mA	

[‡] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

[§] The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, IOS.

switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 4.5$ $C_{L} = 50 \text{ pF}$ $R_{L} = 500 \Omega$ $T_{A} = \text{MIN to}$ SN74A MIN	e, o MAX†	UNIT
t _{PLH}	A sur B	.,	1	6	
tPHL	A or B	Y	1	5.5	ns
^t PLH	- (D	V	2	11	
t _{PHL}	Ā/B	Y	2	10	ns
t _{PLH}	G		2	10.5	ns
t _{PHL}	g	ľ	2	7.5	115

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

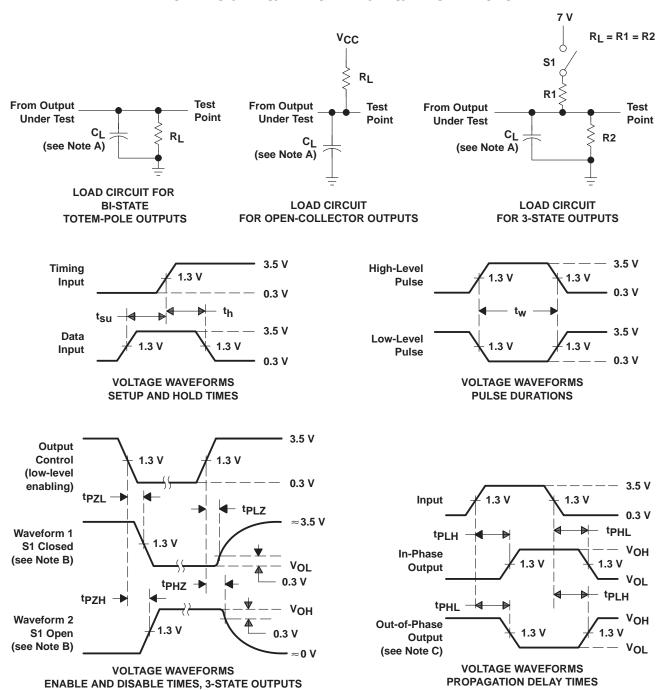
switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 4.5 \ C_L = 50 pF, RL = 500 Ω , TA = MIN to SN74AS	мах†	UNIT
t _{PLH}	. 5	.,	1	5	
t _{PHL}	A or B	Υ	1	4.5	ns
^t PLH	Ā/B	V	2	9.5	
^t PHL	A/B	Y	2	10.5	ns
^t PLH	G	v	2	6.5	ns
^t PHL	9	1	2	10	115

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

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PARAMETER MEASUREMENT INFORMATION SERIES 54ALS/74ALS AND 54AS/74AS DEVICES



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. When measuring propagation delay items of 3-state outputs, switch S1 is open.
- D. All input pulses have the following characteristics: PRR \leq 1 MHz, $t_{\Gamma} = t_{f} = 2$ ns, duty cycle = 50%.
- E. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms



5-Sep-2011

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
5962-86869012A	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Call TI	
5962-8686901EA	ACTIVE	CDIP	J	16	1	TBD	Call TI	Call TI	
5962-8686901FA	ACTIVE	CFP	W	16	1	TBD	Call TI	Call TI	
5962-88625012A	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Call TI	
5962-8862501EA	ACTIVE	CDIP	J	16	1	TBD	Call TI	Call TI	
5962-8862501FA	ACTIVE	CFP	W	16	1	TBD	Call TI	Call TI	
SN54ALS157AJ	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
SN74ALS157AD	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS157ADE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS157ADG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS157ADR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS157ADRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS157ADRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS157AN	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74ALS157AN3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	
SN74ALS157ANE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74ALS157ANSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS157ANSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS157ANSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS158D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS158DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	



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Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
SN74ALS158DG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS158N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74ALS158NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74ALS158NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS158NSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS158NSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74AS157D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74AS157DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74AS157DG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74AS157N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74AS157N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	
SN74AS157NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74AS157NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74AS157NSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74AS157NSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74AS158D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74AS158DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74AS158DG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74AS158N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74AS158NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74AS158NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	



PACKAGE OPTION ADDENDUM



5-Sep-2011

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
SN74AS158NSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74AS158NSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SNJ54ALS157AFK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
SNJ54ALS157AJ	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
SNJ54ALS157AW	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	
SNJ54ALS158FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
SNJ54ALS158J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
SNJ54ALS158W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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OTHER QUALIFIED VERSIONS OF SN54ALS157A, SN54ALS158, SN74ALS157A, SN74ALS158:

● Catalog: SN74ALS157A, SN74ALS158

• Military: SN54ALS157A, SN54ALS158

NOTE: Qualified Version Definitions:

Catalog - TI's standard catalog product

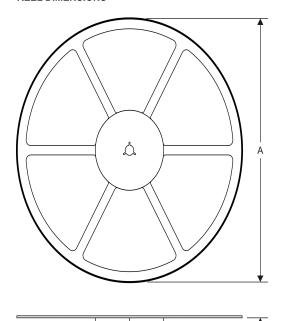
• Military - QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

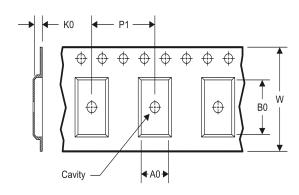
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TAPE AND REEL INFORMATION

REEL DIMENSIONS



TAPE DIMENSIONS



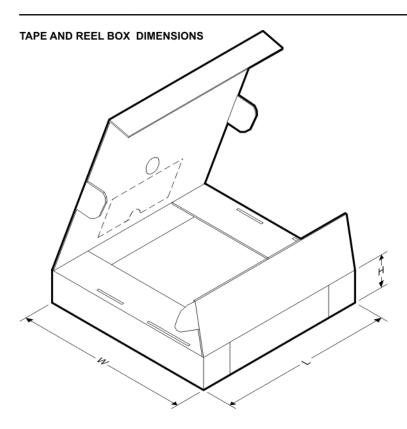
A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device		Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALS157ADR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74ALS157ANSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74ALS158NSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74AS157NSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74AS158NSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

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*All dimensions are nominal

7 til diffictiolofio are florilifiai							
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ALS157ADR	SOIC	D	16	2500	333.2	345.9	28.6
SN74ALS157ANSR	SO	NS	16	2000	367.0	367.0	38.0
SN74ALS158NSR	SO	NS	16	2000	367.0	367.0	38.0
SN74AS157NSR	SO	NS	16	2000	367.0	367.0	38.0
SN74AS158NSR	SO	NS	16	2000	367.0	367.0	38.0

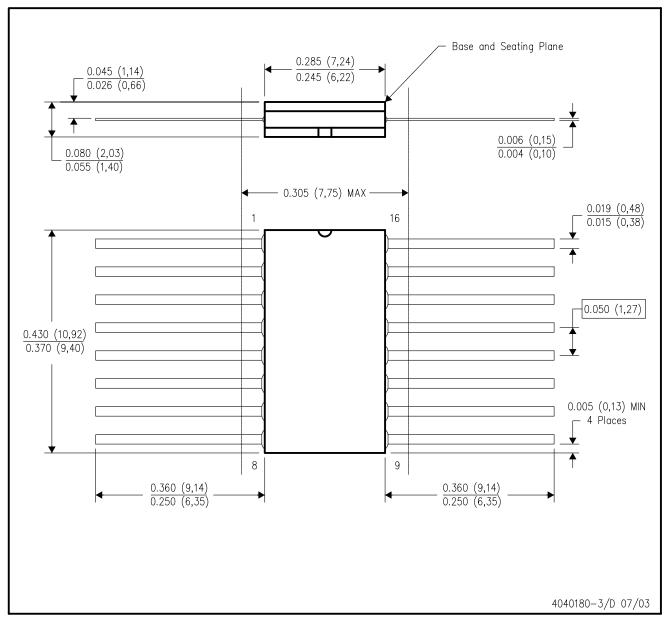
14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F16)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F16 and JEDEC MO-092AC



FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



D (R-PDS0-G16)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



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